

MA22D40

Silicon epitaxial planar type

For high speed switching circuits

■ Features

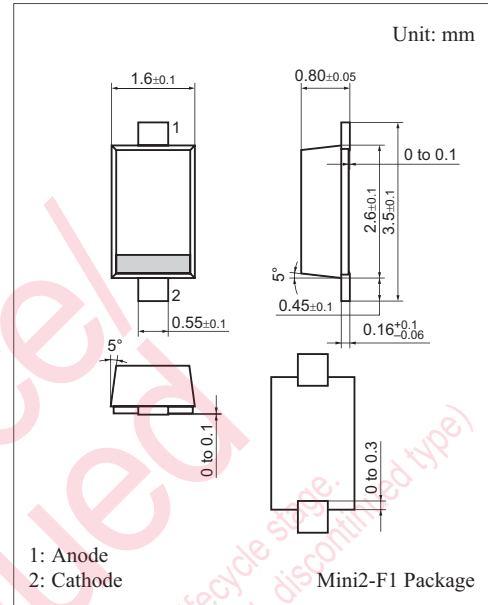
- Reverse voltage $V_R = 60$ V is guaranteed
- Small reverse current I_R

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Maximum peak reverse voltage	V_{RM}	60	V
Forward current *1	I_F	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	30	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Mounted on an alumina PC board

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)



Marking Symbol: 3K

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 1.0$ A		0.50	0.58	V
Reverse current	I_{R1}	$V_R = 30$ V		1	10	μA
	I_{R2}	$V_R = 60$ V		6	30	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

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